IFW/

MEG-02-015

June 14, 2005

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Fr:

Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

10/685,872

10/15/02

M.S. LIN ET AL

"POST PASSIVATION INTERCONNECTION SCHEMES ON TOP OF THE IC CHIPS"

Group Art Unit: 2822

KEVIN M. PICARDAT

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated January 14, 2005, please amend the aboveidentified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 14, 2005.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 6 IUI

MEG-02-015

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of the Claims which begins on page 4 of this paper.

Amendments to the Drawings begin on page 12 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 13 of this paper.

An Appendix including amended drawing figures is attached following page 16 of this paper.